

Company		DUNS#	URL For Additional Information
National Semiconductor		04-147-2986	http://www.national.com/analog/quality/green

Contact	Title	Phone	Email
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Part Number	MSL Rating	Peak Body Temp C	MaxTime(Sec)	Cycles	Unit Type
LMD18200-2D/883SD	1	NA	NA	NA	Each

Document Date	Contains Lead(Pb) - NOT European RoHS NOT China RoHS Compliant.	Weight (mg)	Does NOT Contain Halogens
01-24-2012		5145.52	

Material Composition Declaration for Electronic Products

Item	Weight (mg)	Component	CAS#	Weight (mg)	Item-ppm	Part-ppm
Lid	757.000	Al2O3	1344-28-1	510.218	674,000	99,158
		SiO2	60676-86-0	190.007	251,000	36,927
		MnO2	1313-13-9	26.192	34,600	5,090
		TiO2	13463-67-7	10.901	14,400	2,119
		Fe2O3	1309-37-1	10.901	14,400	2,119
		Cr2O3	1308-38-9	8.781	11,600	1,707
Leadframe	432.000	Fe	7439-89-6	250.560	580,000	48,695
		Ni	7440-02-0	181.440	420,000	35,262
Chip	40.000	Si	7440-21-3	39.760	994,000	7,727
		Al	7429-90-5	0.240	6,000	47
Die Attach	35.800	Ag	7440-22-4	28.640	800,000	5,566
		Lead Borate Glass	65997-18-4	7.160	200,000	1,392
Ext. LeadFinish	34.700	Sn	7440-31-5	21.861	630,000	4,249
		Pb	7439-92-1	12.839	370,000	2,495
Ceramic Body	3309.000	AlN	24304-00-5	3031.044	916,000	589,065
		Er2O3	12061-16-4	271.338	82,000	52,733
		MoO3	1313-27-5	6.618	2,000	1,286
Lid Attach	330.000	PbO	1317-36-8	195.591	592,700	38,012
		ZnO	1314-13-2	63.393	192,100	12,320
		B2O3	1303-86-2	20.757	62,900	4,034
		SiO2	60676-86-0	20.757	62,900	4,034
		TiO2	13463-67-7	18.579	56,300	3,611
		Bi2O3	1304-76-3	5.478	16,600	1,065
		Al2O3	1344-28-1	5.445	16,500	1,058
Brazing	22.200	Ag	7440-22-4	18.870	850,000	3,667
		Cu	7440-50-8	3.330	150,000	647
Metallization	184.599	W	7440-33-7	149.988	812,500	29,149
		Au	7440-57-5	16.983	92,000	3,301
		Ni	7440-02-0	14.378	77,890	2,794
		Mo	7439-98-7	2.160	11,700	420
		Co	7440-48-4	0.620	3,360	120
		Pd	7440-05-3	0.415	2,250	81
		B	7440-42-8	0.055	300	11
Wires	0.216	Al	7429-90-5	0.214	990,000	42
		Si	7440-21-3	0.002	10,000	0

Note: The device content disclosed herewith is approximate and is based on engineering estimates only. It has not been verified through analytical testing.

Additionally, the following should be noted:

- One or more dopant materials may be present in the silicon die at sub-ppm levels to provide semiconductor properties.
- Epoxy resin components listed are generic and may or may not be the specific compound used, which is considered proprietary.

RoHS Material Composition Declaration	
RoHS Directive 2002/95/EC	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

Subject to the limitations below, National Semiconductor Corporation ("National") certifies the following information as of the document date.

1. National products designated "ROHS Compliant" comply with the European Unions Directive on the Restriction of the Use of Hazardous Substances 2002/95/EC ("RoHS"). Certain National products contain lead in RoHS exempt applications 7(a) or 7(c)-1.
2. National products do not contain and are not manufactured with ozone depleting compounds.
3. National products do not contain substances identified by the European Chemical Agency ("ECHA") as substances of very high concern ("SVHC") per REACH Regulation (EC) No 1907/2006. National also complies with use restrictions as stipulated in Annex XVII of REACH.
4. National products are manufactured in conformance with National specifications (SC)CSP-9-111C1 Supplier Environmental Requirements for Materials and Products and (SC)CSP-9-111S2 Banned and Reportable Substances.
5. National's list of banned and reportable substances and management system is based on the current version of the Joint Industrial Guide, JIG-101.

National has taken commercially reasonable steps to provide representative and accurate information but may not have independently verified information provided or conducted chemical analysis of incoming materials. Equivalent compliant materials may have been substituted for those stated herein. Material concentrations are the maximum expected concentration of the substance in the device and may not represent the actual concentration. National and its suppliers consider certain limited information to be confidential and thus CAS numbers and other limited information may not be available for release. National's Standard Terms and Conditions of Sale apply to any issue arising out of or in connection with the information provided herein unless otherwise provided by a written contract signed by both parties.

NATIONAL ACCEPTS NO DUTY TO NOTIFY USERS OF THIS DECLARATION OF UPDATES OR CHANGES TO THIS DECLARATION.



John L. Conn
Vice President Quality

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Vice President Quality

Banned Substance Monitoring

Part Number	Document Date
LMD18200-2D/883SD	01-24-2012

Contains Lead(Pb) - NOT European RoHS Compliant.

NOT China RoHS Compliant.

Item#	Material	Cd	CrVI	Pb	Hg	PBB	PBDE	Cl	Br	Ref#
1	CHIP	<1	<1	<1	<30	<10	<10	<75	<50	1000
2	DIP	<2	<2	95675	<2	<5	<5	N/A	N/A	714
3	EXTLF	<2	N/D	367077	<2	<5	<5	<50	<50	57
4	LID	<2	<2	95675	<2	<5	<5	N/A	N/A	714
5	WIRE	<2	N/D	<2	<2	<5	<5	N/A	N/A	604

* Cd: Cadmium, CrVI: Hexavalent Chromium, Pb: Lead, Hg: Mercury, NA: Not Applicable

* Unless otherwise noted, units are in PPM (parts-per-million)

Ref#	3rd Party Analysis (available upon request, subject to a non-disclosure agreement)
1000	Analysis on 01/24/2011 by Balazs as per Report# 11-00322-00
714	Analysis on 04/29/2011 by SGS per Report# LPCI/04440(B)/11
57	Analysis on 04/29/2011 by SGS per Report# LPCI/04327(B)/11
714	Analysis on 04/29/2011 by SGS per Report# LPCI/04440(B)/11
604	Analysis on 04/29/2011 by SGS per Report# LPCI/04451(B)/11

部件名称 Part	有毒有害物质或元素 Toxic and harmful substances or elements					
	铅 (Pb)	汞 (Hg)	镉 (Cd)	六价铬 (Cr6+)	多溴联苯 (PBB)	多溴二苯醚 (PBDE)
集成电路 Integrated Circuit	X	○	○	○	○	○

○ : 表示该有毒有害物质在该部件所有均质材料中的含量均在SJ/T 11363-2006标准规定的限量要求以下。

○ : Indicates that this hazardous substance contained in all homogeneous materials of this part is below the limit requirement in SJ/T 11363-2006.

X : 表示该有毒有害物质至少在该部件的某一均质材料中的含量超出SJ/T 11363-2006标准规定的限量要求。

X : Indicates that this hazardous substance contained in at least one of the homogeneous materials of this part is above the limit requirement in SJ/T 11363-2006.

美国国家半导体的产品不会含有镉、汞、六价铬、多溴联苯(PBB)和二苯醚(PBDE)。

National Semiconductor's products will not contain cadmium, mercury, hexavalent chromium, polybrominated biphenyls (PBBs) and diphenyl ether (PBDE).



环保使用期限(epup) 是指以符号在这里展出. 环保使用期限(epup)的有效期只有当产品使用范围以内的数据表中的规格.

The Environmental Protection Use Period (EPUP) is defined by the symbol shown here. The Environmental Protection Use Period (EPUP) is valid only when product is used within the limits of the data sheet specifications.